

L Number	Hits	Search Text	DB	Time stamp
1	1779	(438/612).ccls. and @ad<=20020109	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/23 08:47
2	1	bond adj pad with copper with 'Al' and 'buffer'	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/23 08:46
3	11	'bond' and 'pad' with copper with 'Al' and 'buffer'	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/23 08:54
4	284	(438/48).ccls. and @ad<=20020109	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/23 08:47
7	1722	(438/614).ccls. and @ad<=20020109	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/23 10:35
8	573	(257/459).ccls. and @ad<=20020109	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/23 08:49
9	1222	(257/784).ccls. and @ad<=20020109	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/23 10:37
10	1209	(257/786).ccls. and @ad<=20020109	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/23 08:51
11	735	(257/781-782).ccls. and @ad<=20020109	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/23 08:52
12	1392	(257/774).ccls. and @ad<=20020109	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/23 11:44
13	1	'bond pad' with 'copper' with 'Al' and 'buffer'	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/23 08:55
14	1	'bonding pad' with 'copper' with 'Al' and 'buffer'	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/23 08:56
15	122	'bonding pad' with 'Cu' with 'Al'	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/23 09:05
16	117	@ad<=20020109 and 'bonding pad' with 'Cu' with 'Al'	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/23 09:01

29	6	@ad<=20020109 and cu adj 'bonding pad' with 'Al'	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/23 09:03
30	117	@ad<=20020109 and 'bonding pad' with 'Cu' with 'Al'	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/23 09:05
33	1		USPAT	2003/01/23 09:57
34	1		USPAT	2003/01/23 09:57
35	1		USPAT	2003/01/23 09:57
36	1		USPAT	2003/01/23 09:58
49	246	@ad<=20020109 and 'bonding pad' with 'integrated circuit' and 'Cu' and 'Al'	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/23 10:02
50	231	(257/784).ccls. and @ad<=20020109 and 'Copper' and 'aluminum'	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/23 10:38
-	2054	(438/612).ccls. or (438/597).ccls. and @ad<=20020109	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/23 08:44
-	337	((438/612).ccls. or (438/597).ccls. and @ad<=20020109) and copper and aluminum	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/21 11:04
-	74	((438/612).ccls. or (438/597).ccls. and @ad<=20020109) and 'bonding pad' with 'integrated circuit'	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/23 10:01
-	1	((438/612).ccls. or (438/597).ccls. and @ad<=20020109) and Cu adj bonding adj pad with 'integrated circuit'	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/21 11:13
-	6	((438/612).ccls. or (438/597).ccls. and @ad<=20020109) and Copper adj bonding adj pad	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/21 11:14
-	1143	@ad<=20020109 and cu adj 'bonding pad' with 'IMD' or 'intermetal dielectric'	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/21 11:45
-	0	@ad<=20020109 and cu adj 'bonding pad' with 'IMD'	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/21 11:27
-	0	@ad<=20020109 and cu adj 'bonding pad' with 'intermetal dielectric'	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/21 11:27
-	6	@ad<=20020109 and cu adj 'bonding pad' with 'Al'	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/23 09:03

-	3	@ad<=20020109 and cu adj 'bonding pad' and 'IMD'	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/21 11:43
-	1	"3942245".PN.	USPAT	2002/08/21 11:40
-	1	"5075965".PN.	USPAT	2002/08/21 11:40
-	1	"5288006".PN.	USPAT	2002/08/21 11:40
-	1	"5376235".PN.	USPAT	2002/08/21 11:41
-	1	"5384284".PN.	USPAT	2002/08/21 11:41
-	1	"5436412".PN.	USPAT	2002/08/21 11:42
-	0	@ad<=20020109 and copper adj bonding adj pad with 'intermetal dielectric'	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/21 11:45
-	4	@ad<=20020109 and copper adj bonding adj pad and 'intermetal dielectric'	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/21 11:46
-	809	((228/180.21).CCLS.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/21 11:48
-	93	((228/180.21).CCLS.) and bonding adj pad	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/21 11:50
-	9	((228/180.21).CCLS.) and bonding adj pad with copper	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/21 13:32
-	8	((228/180.21).CCLS.) and bond adj pad with copper	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/21 13:30
-	0	((228/180.21).CCLS.) and bond adj pad with copper with 'Al' adj buffer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/23 08:45
-	0	((228/180.21).CCLS.) and bond adj pad with copper with 'Al'	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/21 13:31
-	639	@ad<=20010119 and bonding adj pad with copper	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/21 13:36
-	359	@ad<=20010119 and bonding adj pad with copper and aluminum	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/21 13:47
-	30	@ad<=20010119 and copper adj bonding adj pad and aluminum	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/21 13:59
-	839	@ad<=20010119 and bonding adj pad and aluminum and buffer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/21 14:00

4120 'bonding pad' and apparatus

USPAT; 2002/08/21 15:03

US-PGPUB;

EPO; JPO;

DERWENT;

IBM\_TDB

3573 ((257/459) or (257/676) or (257/786) or  
(275/670) or (257/672)).CCLS.

USPAT; 2002/08/21 15:07

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EPO; JPO;

DERWENT;

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